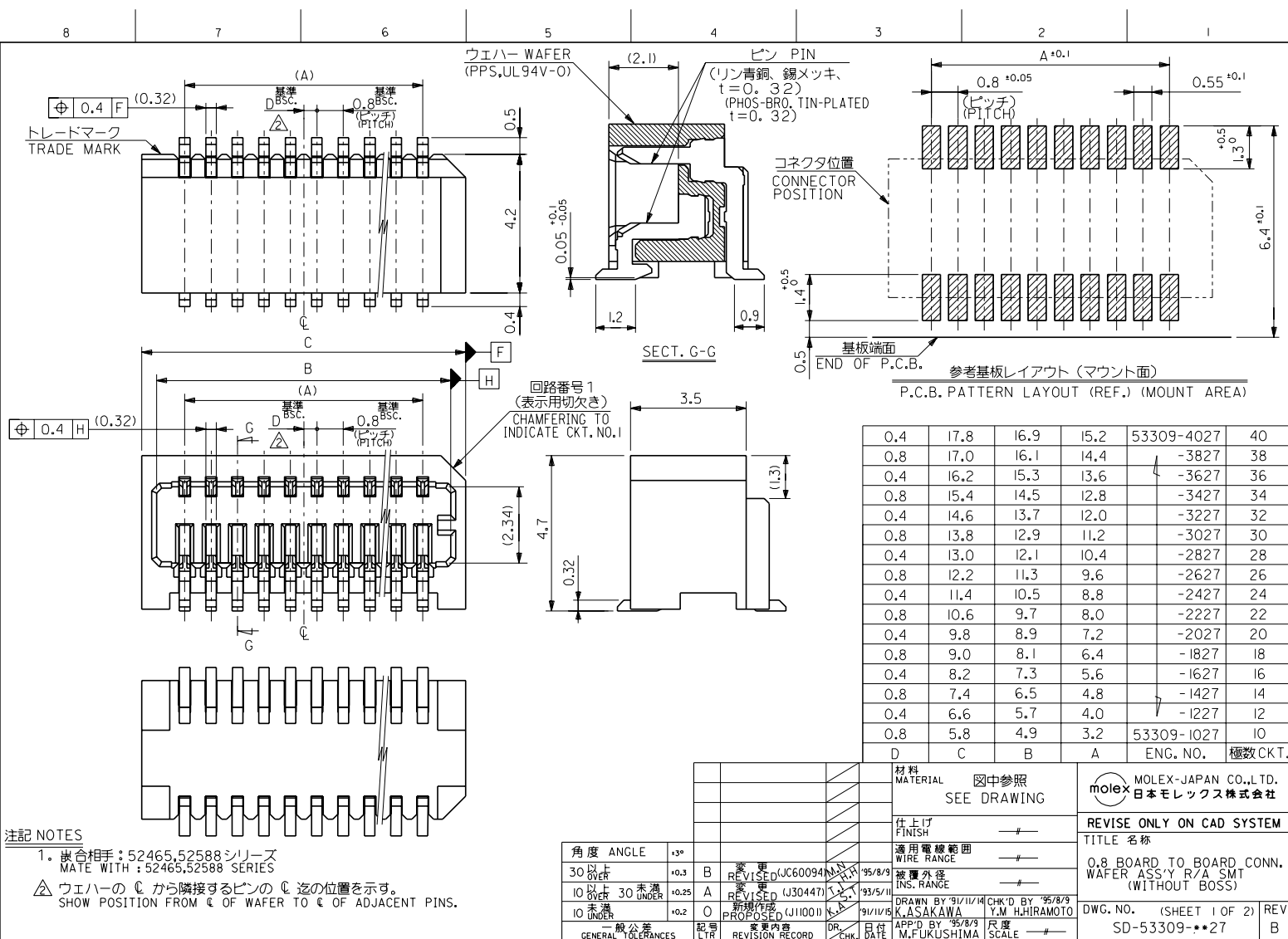


DWG. NO. SD-53309-**-27
 E
 D
 C
 B
 A
 DIMENSIONS IN METRIC DO NOT SCALE DRAWING

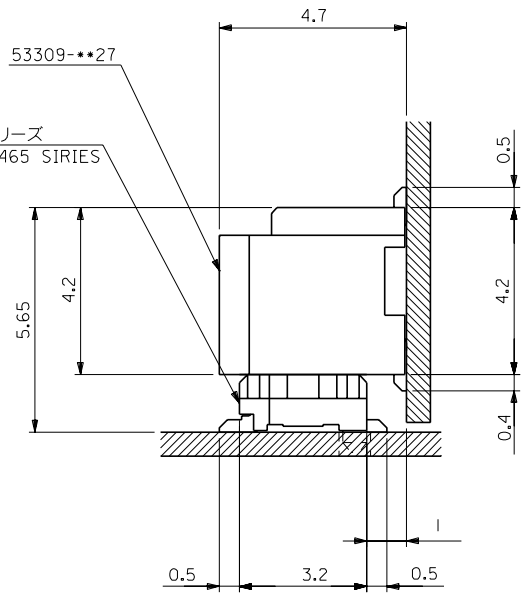


注記 NOTES
 1. 嵌合相手: 52465,52588 シリーズ
 MATE WITH : 52465,52588 SERIES
 △ ウェハの ϕ から隣接するピンの ϕ 迄の位置を示す。
 SHOW POSITION FROM ϕ OF WAFER TO ϕ OF ADJACENT PINS.

DWG. NO. SD-53309-**-27

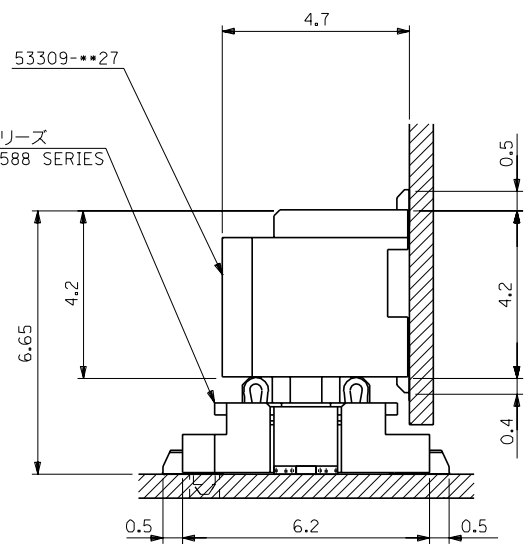
ALL DIMENSIONS IN METRIC DO NOT SCALE DRAWING

嵌合相手 52465 シリーズ
MATES WITH 52465 SERIES



嵌合状態図 (参考)
MATED DRAWING(REF.)

嵌合相手 52588 シリーズ
MATES WITH 52588 SERIES



嵌合状態図 (参考)
MATED DRAWING(REF.)

| | | | | | | | | | | |
|-------------------------|---------|--------|-----------------------|------------|---------|---------------------------------------|------------|-------------------|-----------------|----------|
| 角度 ANGLE | 公差 TOL. | 記号 LTR | 変更内容 REVISION RECORD | DR. / CHK. | 日付 DATE | 材料 MATERIAL | 仕上り FINISH | 適用電線範囲 WIRE RANGE | 被覆外径 INS. RANGE | 尺度 SCALE |
| 30以上 OVER | +0.3 | B | 変更 REVISD(JC60094) | MAN | 95/8/9 | SHEET 1 OF 2 参照 REFER TO SHEET 1 OF 2 | — | — | — | — |
| 10以上 未満 OVER 30 UNDER | +0.25 | A | 変更 REVISD(J30447) | MAN | 93/5/11 | | — | — | — | — |
| 10未満 UNDER | +0.2 | O | 新規作成 PROPOSED(J11001) | MAN | 91/11/6 | | — | — | — | — |
| 一般公差 GENERAL TOLERANCES | | | | | | | | | | |

MOLEX-JAPAN CO.,LTD.
日本モレックス株式会社

REVISE ONLY ON CAD SYSTEM

TITLE 名称
0.8 BOARD TO BOARD CONN.
WAFER ASSY R/A SMT
(WITHOUT BOSS)

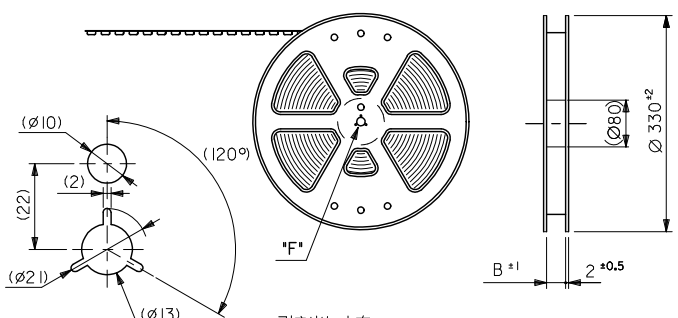
DWG. NO. (SHEET 2 OF 2) REV
SD-53309-**-27 B

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本図面は日本モレックス(株)の所有する情報を含むもので 当社の許可なく複製を禁止する。
EN-01C(032)MXJ-32

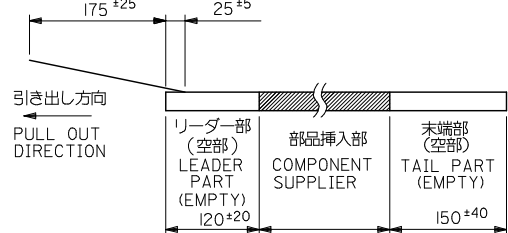
10 9 8 7 6 5 4 3 2 1

引き出し方向
PULL OUT
DIRECTION

注記 NOTES

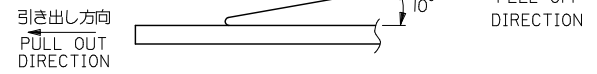


1. 梱包数量：1000個/リール NUMBER OF CONNECTORS:1000PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH
 トップテープ TOP TAPE トップテープ TOP TAPE
 リーダー部 LEADER PART 未接着部 NON-BONDED PART



3. トップテープの剥離強度：(剥離方向は下図参照)
 0.1N~0.7N(10.2gf~71.4gf) 尚、本規格値は、出荷時に適用。
 (但し、輸送時に剥離が発生しない事。)

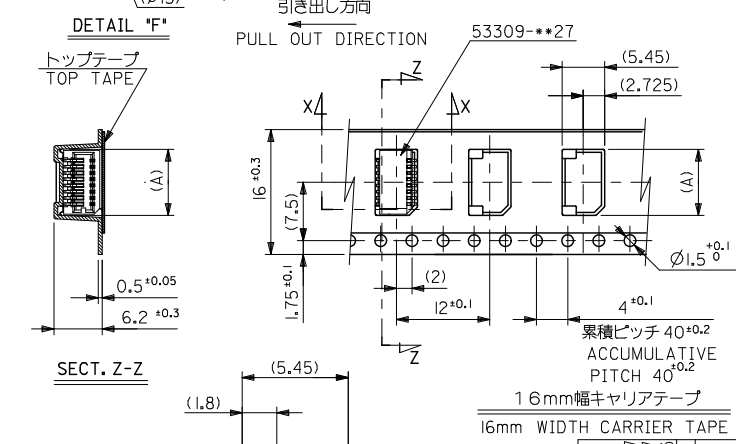
PEELING OFF FORCE OF TOP TAPE
 0.1N~0.7N(10.2gf~71.4gf)(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
 THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
 PEEL OFF SHOULD NOT BE ALLOWED,
 DURING TRANSPORTATION



4. 材料
 キャリアテープ：ポリプロピレン (PP)
 トップテープ：PET, PE, PEF
 リール：ポリスチレン (PS)
 <リサイクル材を含む>

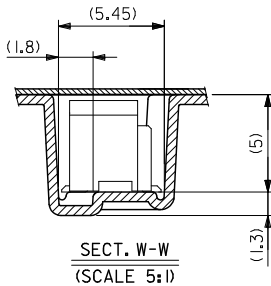
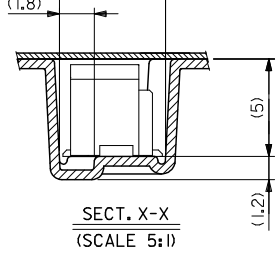
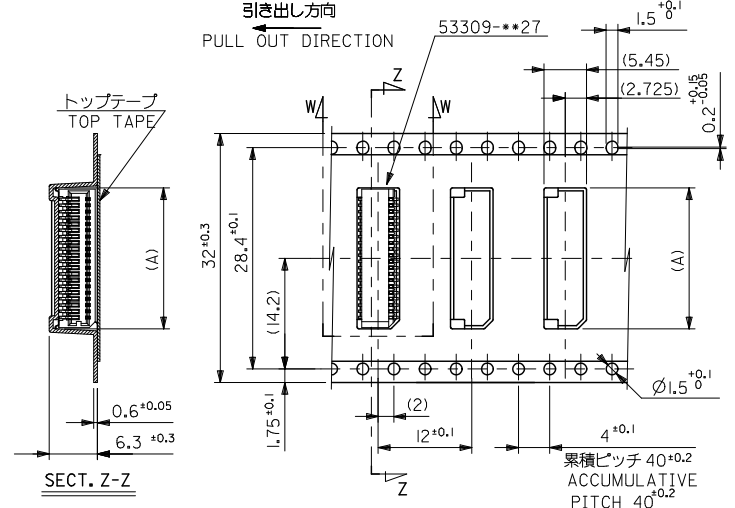
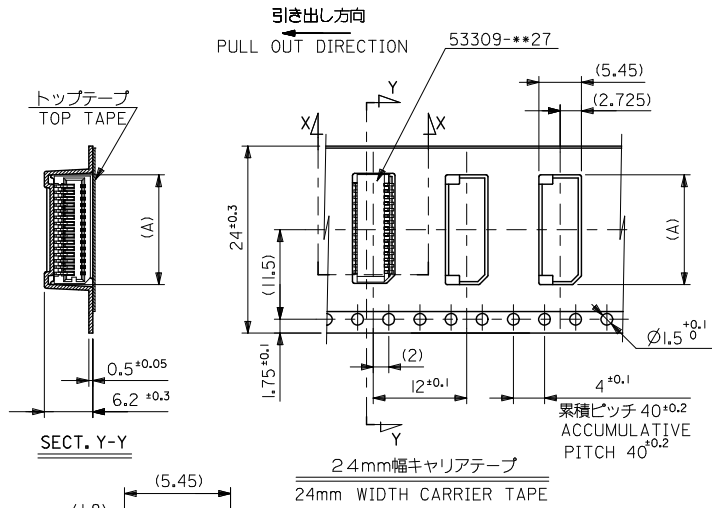
MATERIAL
 CARRIER TAPE:POLYPROPYLENE
 TOP TAPE:PET,PE,PEF
 REEL:POLYSTYRENE(PS)
 <RECYCLE MATERIAL
 CONTAINED>

| | | | | |
|--------------------------------|------|-----|--------------|---------------|
| 16 | 17.5 | 9.3 | 53309-1891 | 18 |
| | | 6.1 | 53309-1091 | 10 |
| キャリアテープ幅 CARRIER TAPE WIDTH | B | (A) | MATERIAL NO. | 極数 CIRCUIT |



| | | | | | | | |
|--|--|--|-----------------------------|---------------------|---|------------------------|----------------------|
| REVISED EC NO: J2009-1528 DRAWN: KURARA 2008/12/17 CHKD: HARUYAMA 2008/12/17 APPR: NIKITA 2009/01/16 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE --- | DESIGN UNITS METRIC | MODEL NO. 53309-**91 |
| | 10 UNDER | ±--- | DRAWN BY K. ASAKAWA | DATE '91/11/22 | TITLE 0.8 BTB CONN WAFER ASSY RA SMT WITHOUT BOSS EMBSTP PAG | | |
| | 10 OVER 30 UNDER | ±--- | CHECKED BY T. ITO | DATE '00/12/6 | MOLEX INCORPORATED | | |
| | 30 OVER | ±--- | APPROVED BY M. FUKUSHIMA | DATE '00/12/6 | DOCUMENT NO. SD-53309-016 | | |
| | ANGULAR ±--- ° | MATERIAL NO. SEE TABLE | | SHEET NO. 1 OF 2 | | | |
| DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | | |

10 9 8 7 6 5 4 3 2 1



| | | | | |
|--------------------------------|------|------|--------------|---------------|
| 32 | 33.5 | 18.1 | 53309-409I | 40 |
| 24 | 25.5 | 14.1 | 53309-309I | 30 |
| | | 10.1 | 53309-209I | 20 |
| キャリアテープ幅 CARRIER TAPE WIDTH | B | (A) | MATERIAL NO. | 極数 CIRCUIT |

MODEL NO. 53309-***91

| | | | | | | |
|---|---------------------------------------|---------|-----------------------------|---|---|------------------------|
| REVISED E.C. NO: J2009-1528 DRAWN: KANAKUBARA 2008/12/17 CHECKED: HARUYAMA 2008/12/17 APPROVED: HARUYAMA 2009/01/16 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | SCALE --- | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION |
| | 10 UNDER | ± --- | DRAWN BY K. ASAKAWA | DATE '91/11/22 | TITLE 0.8 BTB CONN WAFER ASSY RA SMT WITHOUT BOSS EMBSTP PAG | |
| | 10 OVER 30 UNDER | ± --- | CHECKED BY T. ITO | DATE '00/12/16 | MOLEX INCORPORATED | |
| | 30 OVER | ± --- | APPROVED BY M. FUKUSHIMA | DATE '00/12/16 | DOCUMENT NO. SD-53309-016 | SHEET NO. 2 OF 2 |
| | ANGULAR | ± --- ° | MATERIAL NO. SEE TABLE | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | |
| DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | | | | | |